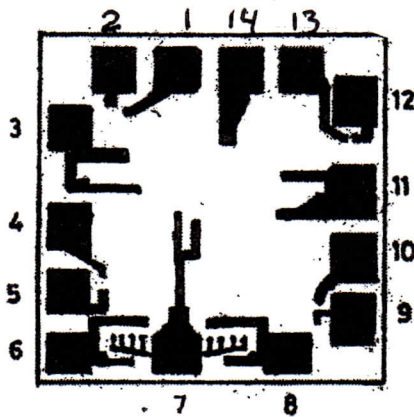




# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



### PIN OUTS:

- 1. 1A-Input
- 2. 1B-Input
- 3. 1Y-Output
- 4. 2A-Input
- 5. 2B-Input
- 6. 2Y-Output
- 7. GND
- 8. 3Y-Output
- 9. 3A-Input
- 10. 3B-Input
- 11. 4Y-Output
- 12. 4A-Input
- 13. 4B-Input
- 14. V

Top Material: Al  
 Backside Material: Si  
 Bond Pad Size: .004" X .004"  
 Backside Potential:  
 Mask Ref:

APPROVED BY: DK

DIE SIZE .039" X .039"

DATE: 5/23/13

MFG: National Semi

THICKNESS .010"

P/N: 5438